Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	ti.com/support
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	06/09/2022

Details for "TLV9351QDBVRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV9351QDBVRQ1	NIPDAU	Level-1-260C-UNLIM	TI PHILIPPINES A/T	DBV 5	2.9x1.6x1.45	32.3

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

			Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.017949	97.586038	975860	0.055649	556
Not Categorized	Proprietary Materials		0.000002	0.010874	109	0.000006	0
Precious Metals	Palladium	7440-05-3	0.000441	2.397651	23977	0.001367	14
Precious Metals	Silver	7440-22-4	0.000001	0.005437	54	0.000003	0
Sub-Total			0.018393	100	1000000	0.057026	570
Die Attach Adhesive	-				•		
Precious Metals	Silver	7440-22-4	0.08087	74.999768	749998	0.250731	2507
Thermoplastics	Ероху	85954-11-6	0.026957	25.000232	250002	0.083578	836
Sub-Total			0.107827	100	1000000	0.334308	3343
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	19.439115	97.05	970500	60.26931	602693
Copper and Its Alloys	Iron	7439-89-6	0.52078	2.6	26000	1.614634	16146
Copper and Its Alloys	Phosphorus	7723-14-0	0.030045	0.15	1500	0.093152	932
Zinc and Its Alloys	Zinc	7440-66-6	0.04006	0.2	2000	0.124203	1242
Sub-Total			20.03	100	1000000	62.101298	621013
Lead Frame Plating		•			· · · · · · · · · · · · · · · · · · ·		
Nickel and Its Alloys	Nickel	7440-02-0	0.066584	95.12	951200	0.206438	2064
Precious Metals	Gold	7440-57-5	0.000546	0.78	7800	0.001693	17
Precious Metals	Palladium	7440-05-3	0.00287	4.1	41000	0.008898	89
Sub-Total			0.07	100	1000000	0.217029	2170
Mold Compound		•			· · · · · · · · · · · · · · · · · · ·		
Other Inorganic Materials	Fused Silica	60676-86-0	10.359921	87.999996	880000	32.120047	321200
Other Organic Materials	Chlorine	7782-50-5	0.000118	0.001002	10	0.000366	4
Other Plastics and Rubber	Carbon Black	1333-86-4	0.035318	0.300001	3000	0.1095	1095
Thermoplastics	Ероху	85954-11-6	1.377281	11.699001	116990	4.270142	42701
Sub-Total			11.772638	100	1000000	36.500055	365001
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.254896	100	1000000	0.790283	7903
Sub-Total			0.254896	100	1000000	0.790283	7903
Total			22 252754			100	1000000
			52.255754			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.